





BASE

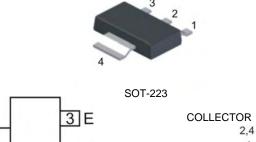
**EMITTER** 

## **Features**

- Epitaxial Planar Die Construction
- Complementary PNP Type Available (DZT951)
- Ideally Suited for Automated Assembly Processes
- Ideal for Medium Power Switching or Amplification Applications
- Lead Free By Design/RoHS Compliant (Note 1)
- "Green" Device (Note 2)

### **Mechanical Data**

- Case: SOT-223
- Case Material: Molded Plastic, "Green" Molding Compound.
  UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020C
- Terminals: Finish Matte Tin annealed over Copper Leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208
- Marking & Type Code Information: See Page 3
- Ordering Information: See Page 3
- Weight: 0.115 grams (approximate)



TOP VIEW Schematic and Pin Configuration

## **Maximum Ratings** @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V <sub>CBO</sub>	150	V
Collector-Emitter Voltage	V <sub>CEO</sub>	60	V
Emitter-Base Voltage	$V_{EBO}$	6	V
Continuous Collector Current	I <sub>C</sub>	6	Α
Power Dissipation	P <sub>tot</sub>	1(Note 3) 3(Note 4)	W
Operating and Storage Temperature Range	$T_j, T_{STG}$	-55 to +150	°C

Notes:

- 1. No purposefully added lead.
- 2. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead\_free/index.php.
- 3. Device mounted on FR-4 PCB, pad layout as shown on page 4.
- 4. The power which can be dissipated, assuming the device is mounted in a typical manner on a PCB with copper equal to 4 square inch minimum.



#### **Electrical Characteristics** @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition			
OFF CHARACTERISTICS									
Collector-Base Breakdown Voltage	V <sub>(BR)CBO</sub>	150	_	_	V	$I_C = 100 \mu A, I_E = 0$			
Collector-Emitter Breakdown Voltage	$V_{(BR)CEO}$	60	_	_	V	$I_C = 10 \text{mA*}, I_B = 0$			
Emitter-Base Breakdown Voltage	$V_{(BR)EBO}$	6	_	_	V	$I_E = 100 \mu A, I_C = 0$			
Collector Cutoff Current		_		50 1	nA μA	$V_{CB} = 120V, I_E = 0$ $V_{CB} = 120V, I_E = 0, T_A = 100^{\circ}C$			
Emitter Cutoff Current	I <sub>EBO</sub>	_		10	nA	$V_{EB} = 6V$ , $I_C = 0$			
ON CHARACTERISTICS									
Collector-Emitter Saturation Voltage	V <sub>CE(SAT)</sub>	_ _ _		50 100 170 375	mV	$\begin{split} I_C &= 0.1A,\ I_B = 5mA^* \\ I_C &= 1A,\ I_B = 50mA^* \\ I_C &= 2A,\ I_B = 50mA^* \\ I_C &= 6A,\ I_B = 300mA^* \end{split}$			
Base-Emitter Saturation Voltage	$V_{BE(SAT)}$	_	_	1200	mV	I <sub>C</sub> = 6A, I <sub>B</sub> = 300mA*			
Base-Emitter Turn-On Voltage	$V_{BE(ON)}$	_	_	1150	mV	I <sub>CE</sub> = 6A, V <sub>CE</sub> = 1V*			
DC Current Gain		100 100 75 25		300 —	_	$\begin{split} I_{C} &= 10 m A, \ V_{CE} = 1 V^{*} \\ I_{C} &= 2 A, \ V_{CE} = 1 V^{*} \\ I_{C} &= 5 A, \ V_{CE} = 1 V^{*} \\ I_{C} &= 10 A, \ V_{CE} = 1 V^{*} \end{split}$			
SMALL SIGNAL CHARACTERISTICS									
Current Gain-Bandwidth Product	f⊤	_	130		MHz	$I_{C} = 100 \text{mA}, V_{CE} = 10 \text{V},$ f = 50MHz			
Output Capacitance	$C_{obo}$		45	_	pF	V <sub>CB</sub> = 10V, f = 1MHz			
Switching Times	t <sub>on</sub> t <sub>off</sub>	_	45 1100		ns	$I_C = 1A$ , $I_{B1} = 100mA$ $I_{B2} = 100mA$ , $V_{CC} = 10V$			

Measured under pulsed conditions. Pulse width =  $300 \mu s$ . Duty cycle  $\leq 2\%$ 

#### **Typical Characteristics** @T<sub>amb</sub> = 25°C unless otherwise specified

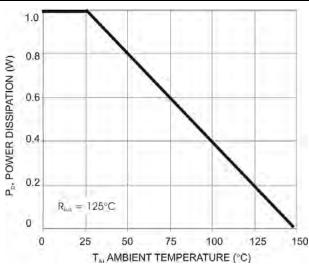


Fig. 1 Power Dissipation vs. Ambient Temperature (Note 3)

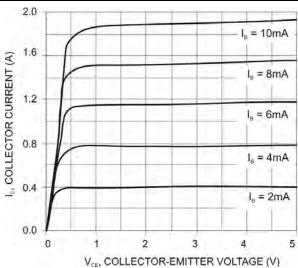


Fig. 2 Collector Current vs. Collector Emitter Voltage

3. Device mounted on FR-4 PCB, pad layout as shown on page 4.



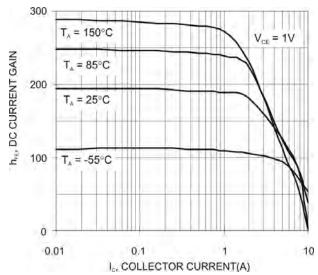


Fig. 3 Typical DC Current Gain vs. Collector Current

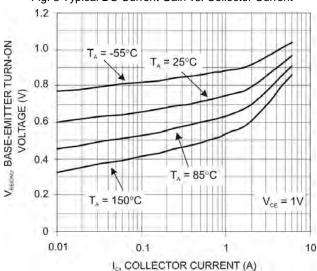


Fig. 5 Base-Emitter Turn-On Voltage vs. Collector Current

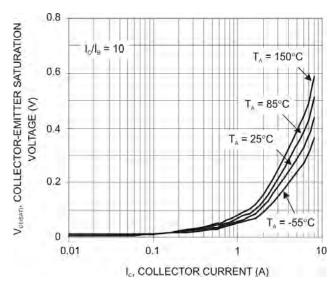


Fig. 4 Collector-Emitter Saturation Voltage vs. Collector Current

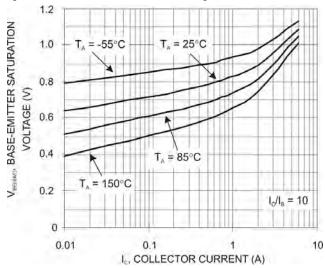


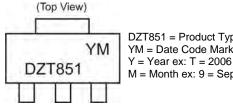
Fig. 6 Base-Emitter Saturation Voltage vs. Collector Current

## **Ordering Information** (Note 5)

Device	Packaging	Shipping
DZT851-13	SOT-223	2500/Tape & Reel

Notes: 5. Packaging Details as shown on page 4, or go to our website at http://www.diodes.com/ap2007.pdf.

# **Marking Information**



DZT851 = Product Type Marking Code YM = Date Code Marking

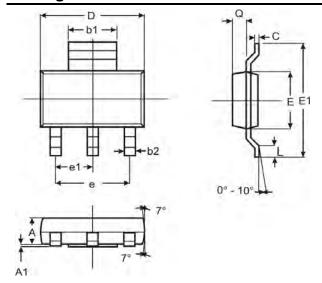
M = Month ex: 9 = September

Data Cada Kay

Date	e Code Key												
	Year 2006		6	2007 2008		20	2009			2011	:	2012	
	Code	Т		U		V	V	V	Х		Υ		Z
	Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
	Code	1	2	3	4	5	6	7	8	9	0	N	D

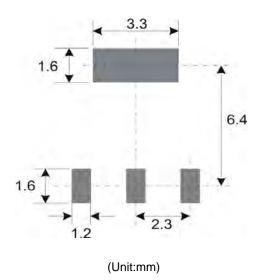


## **Package Outline Dimensions**



SOT-223								
Dim	Min	Max	Тур					
Α	1.55	1.65	1.60					
<b>A</b> 1	0.010	0.15	0.05					
b1	2.90	3.10	3.00					
b2	0.60	0.80	0.70					
С	0.20	0.30	0.25					
D	6.45	6.55	6.50					
Е	3.45	3.55	3.50					
E1	6.90	7.10	7.00					
е		1	4.60					
e1			2.30					
L	0.85	1.05	0.95					
Q	0.89							
All Dimensions in mm								

# Suggested Pad Layout: (Based on IPC-SM-782)



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